

SOT962-2

plastic thin fine-pitch ball grid array package; 64 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA64
Package type industry code	TFBGA64
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-6-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.4	-	4.5	4.6	mm
E	package width		4.4	-	4.5	4.6	mm
A	seated height		1	-	1.1	1.2	mm
A ₂	package height		0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination		-	-	64	-	



2. Package outline

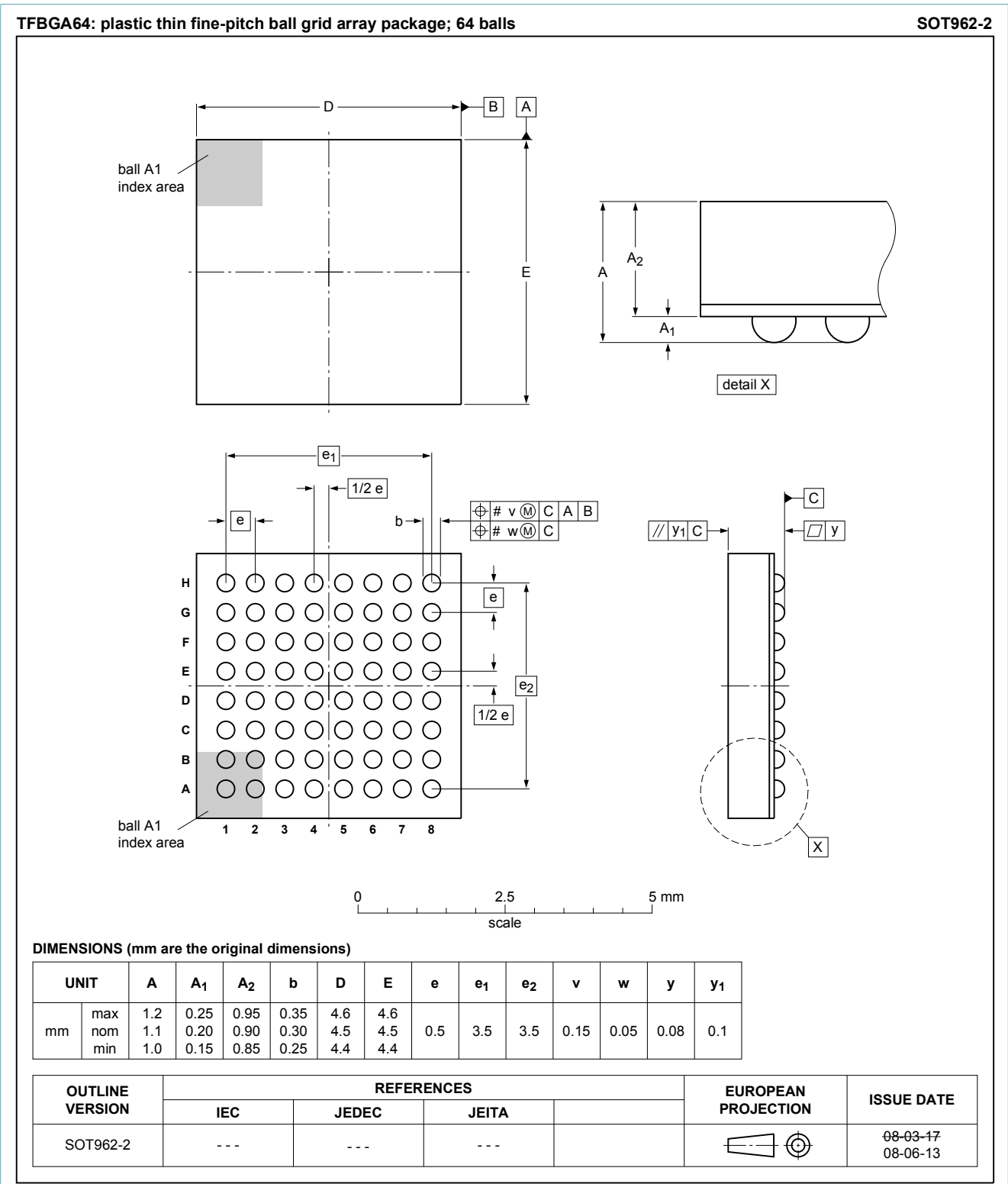
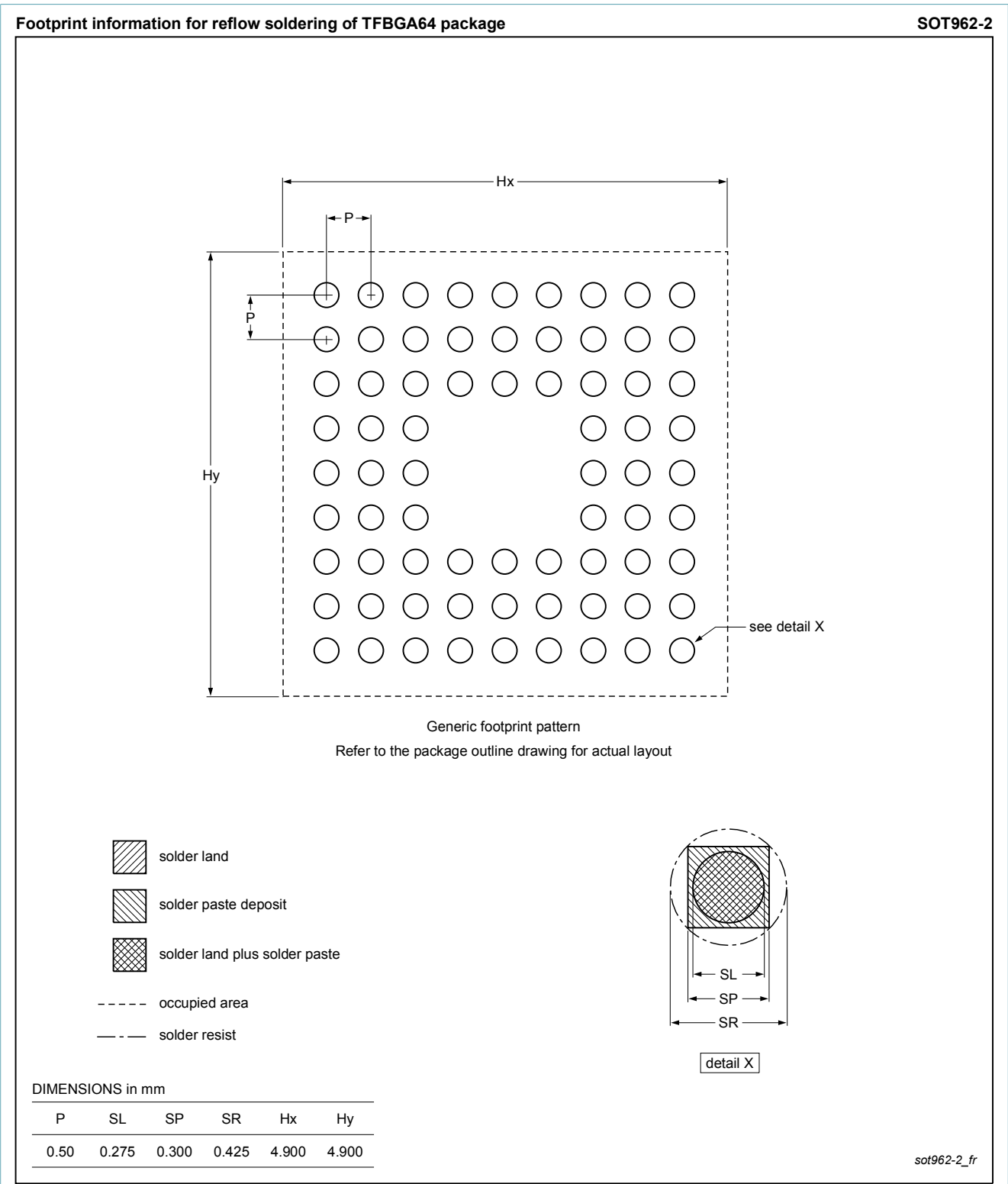


Fig. 1. Package outline TFBGA64 (SOT962-2)

3. Soldering



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Fig. 2. Reflow soldering footprint for TFBGA64 (SOT962-2)

4. Legal information

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